

Application Data Sheet

APPLICATION INFORMATION

Application Number::

Filing Date::

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R?:: None

Number of CD Disks:

Number of Copies of CDs::

Sequence Submission?::

Computer Readable From (CRF)?:: No

Number of Copies of CRF::

Title:: SEMICONDUCTOR WAFER PROCESSING
APPARATUS

Attorney Docket Number:: 402734

Request for Early Publication?:: No

Request for Non-Publication?:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 10

Small Entity?:: No

Latin Name::

Variety denomination name::

Petition Included?:: No

Petition Type::

Licensed US Govt. Agency::

Contract or Grant Numbers::

Secrecy Order in Parent Appl.?:: No

APPLICANT INFORMATION

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Takayuki
Middle Name::	
Family Name::	SHOYA
Name Suffix::	
City of Residence::	Kumamoto-shi
State or Province of Residence::	Kumamoto
Country of Residence::	Japan
Street of mailing address::	103, Hakenomiyafuratto 4-3-73 Hakenomiya
City of mailing address::	Kumamoto-shi
State or Province of mailing address::	Kumamoto
Country of mailing address::	Japan
Postal or Zip Code of mailing address::	860-0864

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Masaru
Middle Name::	
Family Name::	NAGANO
Name Suffix::	
City of Residence::	Hyogo
State or Province of Residence::	
Country of Residence::	Japan
Street of mailing address::	c/o Renesas Semiconductor Engineering Corp. 4-1, Mizuhara

City of mailing address:: Itami-shi
State or Province of mailing address:: Hyogo
Country of mailing address:: Japan
Postal or Zip Code of mailing address:: 664-0005

CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 23548
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REPRESENTATIVE INFORMATION

Representative Customer Number:: 23548

Representative Designation:: Registration Number:: Representative Name::

DOMESTIC PRIORITY INFORMATION

Application:: Continuity Type:: Parent Application:: Parent Filing Date::

FOREIGN APPLICATION INFORMATION

Country::	Application Number::	Filing Date::	Priority Claimed
Japan	2003-017269	01/27/03	Yes

ASSIGNEE INFORMATION

Assignee name:: Renesas Technology Corp.
Street of mailing address:: 4-1, Marunouchi 2-chome
 Chiyoda-ku
City of mailing address:: Tokyo
State or Province of
mailing address::
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address:: Japan
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